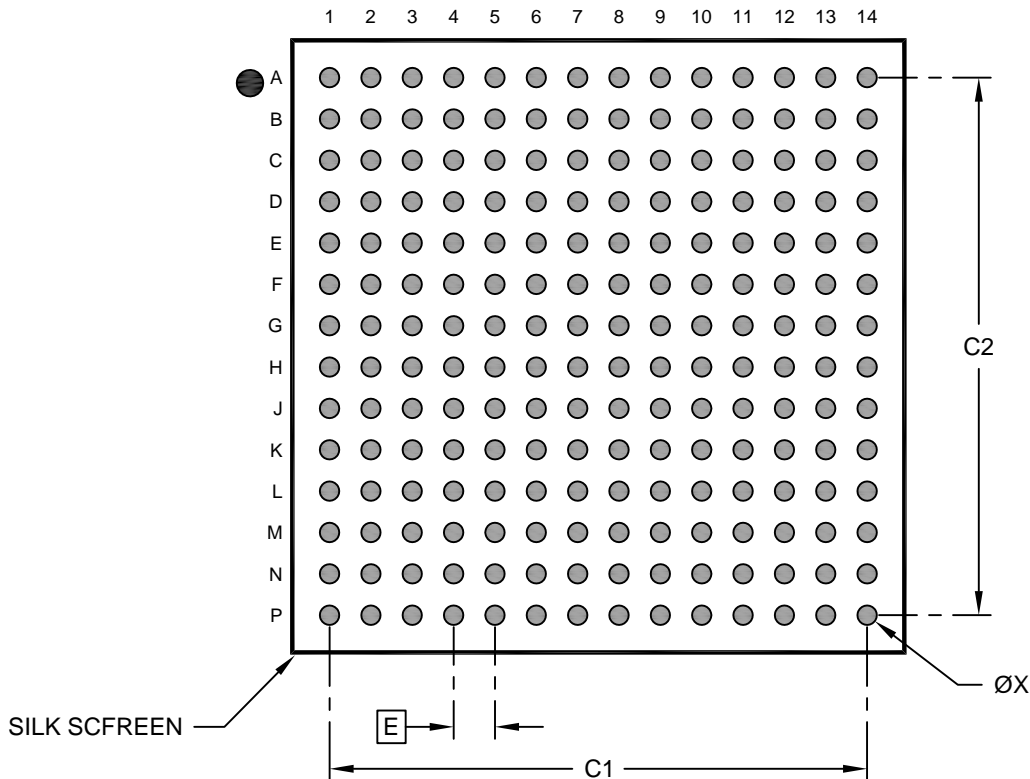


196-Ball Thin Fine Pitch Ball Grid Array (BAB) - 11x11 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Contact Pitch	E		0.75 BSC		
Contact Pad Spacing	C1			9.75	
Contact Pad Spacing	C2			9.75	
Contact Pad Diameter (X196)	X				0.35

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.